

Hui Yang

List of Publications by Year in descending order

Source: <https://exaly.com/author-pdf/723669/publications.pdf>

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7
papers

50
citations

1684188
5
h-index

1720034
7
g-index

7
all docs

7
docs citations

7
times ranked

35
citing authors

#	ARTICLE	IF	CITATIONS
1	Fatigue life of solder joints in nanosilver tin paste in chip interconnect. <i>Fatigue and Fracture of Engineering Materials and Structures</i> , 2022, 45, 323-327.	3.4	1
2	Influencing Factors of Fatigue Life of Nano-Silver Paste in Chip Interconnection. <i>Journal of Electronic Materials</i> , 2021, 50, 224-232.	2.2	6
3	Stacked Auto-Encoder Network to Predict Tensile Deformation Behavior of a Typical Nickel-Based Superalloy Considering Portevin-Le Chatelier Effects. <i>Metals and Materials International</i> , 2021, 27, 254-261.	3.4	7
4	Preparation and sintering characteristics of nanosilver-tin core-shell paste. <i>Journal of Materials Science: Materials in Electronics</i> , 2021, 32, 11202-11209.	2.2	1
5	Influences of feed rate and wall thickness reduction on the microstructures of thin-walled Hastelloy C-276 cylindrical parts during staggered spinning. <i>International Journal of Advanced Manufacturing Technology</i> , 2020, 106, 3809-3821.	3.0	8
6	Study on the main influencing factors of shear strength of nano-silver joints. <i>Journal of Materials Research and Technology</i> , 2020, 9, 4133-4138.	5.8	8
7	Influences of Initial Microstructures on Portevin-Le Chatelier Effect and Mechanical Properties of a Ni-Fe-Cr Base Superalloy. <i>Advanced Engineering Materials</i> , 2018, 20, 1800234.	3.5	19